

# Bill of Materials

 TI DESIGNS  
 PMP7919

Designator	Description	PartNumber
AA1	Printed Circuit Board	551XX7850-001 REV B
C1	CAP, CERM, 470pF, 100V, +/-5%, C0G/NP0, 0805	GRM2165C2A471JA01D
C2	CAP, CERM, 470pF, 100V, +/-5%, C0G/NP0, 0805	GRM2165C2A471JA01D
C3	CAP, AL, 330uF, 10V, +/-20%, SMD	10SVPS330M
C4	CAP, AL, 180uF, 16V, +/-20%, SMD	16SVP180MX
C5	CAP, AL, 180uF, 16V, +/-20%, SMD	16SVP180MX
C6	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206	C3216X5R1C106M
C7	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206	C3216X5R1C106M
C8	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206	C3216X5R1C106M
C9	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206	C3216X5R1C106M
C10	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206	C3216X5R1C106M
C11	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603	GRM188R71E474KA12D
C12	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	GRM1885C1H101JA01D
C13	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603	GRM188R71E474KA12D
C14	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	GRM188R71E105KA12D
C15	CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0603	GRM188R71E104KA01D
C16	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	GRM1885C1H101JA01D
C17	CAP, CERM, 0.047uF, 25V, +/-10%, X7R, 0603	GRM188R71E473KA01D
C18	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	GRM1885C1H101JA01D
C19	CAP, CERM, 470pF, 100V, +/-5%, C0G/NP0, 0805	GRM2165C2A471JA01D
C20	CAP, CERM, 0.022uF, 25V, +/-10%, X7R, 0603	C0603C223K3RACTU
C21	CAP, CERM, 470pF, 100V, +/-5%, C0G/NP0, 0805	GRM2165C2A471JA01D
C22	CAP, AL, 180uF, 16V, +/-20%, SMD	16SVP180MX
C23	CAP, AL, 180uF, 16V, +/-20%, SMD	16SVP180MX
C24	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206	C3216X5R1C106M
C25	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206	C3216X5R1C106M
C26	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206	C3216X5R1C106M
C27	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206	C3216X5R1C106M
C28	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206	C3216X5R1C106M
C29	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603	GRM188R71E474KA12D
C30	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	GRM1885C1H101JA01D
C31	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603	GRM188R71E474KA12D
C32	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	GRM188R71E105KA12D
C33	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	GRM1885C1H101JA01D
C34	CAP, CERM, 0.01uF, 16V, +/-10%, X7R, 0603	GRM188R71C103KA01D
D1	Diode, Schottky, 60V, 1A, SOD-123F	PMEG6010CEH,115
D3	Diode, Schottky, 60V, 1A, SOD-123F	PMEG6010CEH,115
D4	Diode, Schottky, 60V, 1A, SOD-123F	PMEG6010CEH,115
D5	Diode, Schottky, 60V, 1A, SOD-123F	PMEG6010CEH,115
IN1	Test Point, TH, Miniature, White	5002
J1	Standard Banana Jack, Uninsulated, 5.5mm	575-4
J2	Standard Banana Jack, Uninsulated, 5.5mm	575-4
J3	Standard Banana Jack, Uninsulated, 5.5mm	575-4
J4	Standard Banana Jack, Uninsulated, 5.5mm	575-4
L1	INDUCTOR POWER 3.3UH 54A SMD	IHLP6767GZER3R3MA1
L2	INDUCTOR POWER 3.3UH 54A SMD	IHLP6767GZER3R3MA1
OUT1	Test Point, TH, Miniature, White	5002

AA1	Printed Circuit Board	551XX7850-001 REV B
Q1	MOSFET N-CH 25V 8SON	CSD16415Q5
Q2	MOSFET N-CH 25V 8SON	CSD16415Q5
Q3	MOSFET N-CH 25V 8SON	CSD16415Q5
Q4	MOSFET N-CH 25V 8SON	CSD16415Q5
Q5	MOSFET N-CH 25V 8SON	CSD16415Q5
Q6	MOSFET N-CH 25V 8SON	CSD16415Q5
Q7	MOSFET N-CH 25V 8SON	CSD16415Q5
Q8	MOSFET N-CH 25V 8SON	CSD16415Q5
R1	RESISTOR 7.5 OHM 3/4W 5% 2010	ERJ-12ZYJ7R5U
R2	RESISTOR 7.5 OHM 3/4W 5% 2010	ERJ-12ZYJ7R5U
R3	RES, 0.0015 ohm, 1%, 1W, 2512	ERJ-M1WTF1M5U
R4	RES, 0 ohm, 5%, 0.1W, 0603	ERJ-3GEY0R00V
R5	RES, 100 ohm, 1%, 0.1W, 0603	CRCW0603100RFKEA
R6	RES, 100 ohm, 1%, 0.1W, 0603	CRCW0603100RFKEA
R7	RES, 0 ohm, 5%, 0.1W, 0603	ERJ-3GEY0R00V
R8	RES, 0 ohm, 5%, 0.1W, 0603	ERJ-3GEY0R00V
R9	RES, 158k ohm, 1%, 0.1W, 0603	CRCW0603158KFKEA
R10	RES, 45.3k ohm, 1%, 0.1W, 0603	CRCW060345K3FKEA
R11	RES, 3.3 ohm, 5%, 0.1W, 0603	CRCW06033R30JNEA
R12	RES, 15.0k ohm, 1%, 0.1W, 0603	RC0603FR-0715KL
R13	RES, 0 ohm, 5%, 0.1W, 0603	ERJ-3GEY0R00V
R14	RES, 0 ohm, 5%, 0.1W, 0603	ERJ-3GEY0R00V
R15	RES, 0 ohm, 5%, 0.1W, 0603	ERJ-3GEY0R00V
R16	RES, 20.0k ohm, 1%, 0.1W, 0603	CRCW060320K0FKEA
R17	RES, 39.0k ohm, 1%, 0.1W, 0603	RC0603FR-0739KL
R18	RES, 15.0k ohm, 1%, 0.1W, 0603	CRCW060315K0FKEA
R19	RESISTOR 7.5 OHM 3/4W 5% 2010	ERJ-12ZYJ7R5U
R20	RES, 2.67k ohm, 1%, 0.1W, 0603	CRCW06032K67FKEA
R21	RES, 23.2k ohm, 1%, 0.1W, 0603	CRCW060323K2FKEA
R22	RES, 604 ohm, 1%, 0.125W, 0805	CRCW0805604RFKEA
R23	RESISTOR 7.5 OHM 3/4W 5% 2010	ERJ-12ZYJ7R5U
R24	RES, 0.0015 ohm, 1%, 1W, 2512	ERJ-M1WTF1M5U
R25	RES, 100 ohm, 1%, 0.1W, 0603	CRCW0603100RFKEA
R26	RES, 100 ohm, 1%, 0.1W, 0603	CRCW0603100RFKEA
R27	RES, 0 ohm, 5%, 0.1W, 0603	ERJ-3GEY0R00V
R28	RES, 0 ohm, 5%, 0.1W, 0603	ERJ-3GEY0R00V
R29	RES, 3.3 ohm, 5%, 0.1W, 0603	CRCW06033R30JNEA
R30	RES, 0 ohm, 5%, 0.1W, 0603	ERJ-3GEY0R00V
R31	RES, 0 ohm, 5%, 0.1W, 0603	ERJ-3GEY0R00V
R32	RES, 0 ohm, 5%, 0.1W, 0603	ERJ-3GEY0R00V
R33	RES, 20.0k ohm, 1%, 0.1W, 0603	CRCW060320K0FKEA
R34	RES, 39.0k ohm, 1%, 0.1W, 0603	RC0603FR-0739KL
Sync In 1	Test Point, TH, Miniature, White	5002
Sync In 2	Test Point, TH, Miniature, White	5002
TP5	Test Point, TH, Miniature, White	5002
TP6	Test Point, TH, Miniature, White	5002
U1	Synchronous Boost Controller	LM5122MH
U2	Synchronous Boost Controller	LM5122MH
Vin1	Test Point, TH, Miniature, Red	5000
Vin Gnd1	Test Point, TH, Miniature, Black	5001
Vout1	Test Point, TH, Miniature, Red	5000
Vout Gnd1	Test Point, TH, Miniature, Black	5001

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